

As advertised in
Electronic Cooling,
Nov 2008 Edition

Saint-Gobain CLOSING THE GAP

Between promises and performance
Between indifference and responsiveness
Between high prices and true value

The gap between your circuit boards and heat sinks isn't the only one you need to consider. There's also the gap between the price you're paying for thermal interface materials and the performance they provide.

Saint-Gobain is committed to closing both these gaps. Our new line of highly compliant gap fillers meets your critical performance requirements at an extremely competitive price. They allow for minimal compression force on sensitive components while delivering maximum thermal conductivity, and are available in an industry-leading 24" x 24" sheet size.



- **TC2006** — The softest 1.6 W/mK thermally conductive gap filler on the market.



- **TC3006** — Outstanding compression performance; allows >45% compression without exceeding 10 psi on components.



- **TC3008** — High performance gap filler (3 W/mK) that maintains excellent compression latitude.

Samples available for immediate delivery.

Simply the coolest
**THERMA
COOL®**

Saint-Gobain is committed to raising the bar on product performance, customer service and — most important — value.

www.thermacool.saint-gobain.com to learn more about Saint-Gobain thermal interface materials.

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